

Yi-Chang Lin

07/19/2022

Application for 2023 Summer Software Development Engineer Internship

Amazon.com, Inc.

USA, Seattle, WA

Dear Hiring Manager,

My name is Yi-Chang Lin, and I am pleased to apply for the 2023 Summer Software Development Engineer Internship at Amazon. The company has been famous for its e-commerce services and Cloud Computing, and it is my dream to join the development of cutting-edge information technologies. I possess various skills and knowledge needed in software engineering therefore I believe I would be a great fit for your team.

Currently, I am a first-year Master of Computer Science student at Rice University. I am proficient and skilled in Python, C, C++, PHP, SQL, Java, and HTML. Before I came to the U.S., I was a teaching assistant at National Yang Ming Chiao Tung University. In the course *Introduction to Computers and C Programming*, I designed several contest-level algorithmic puzzles to sharpen students' coding skills. In the course *Introduction to Database Systems*, I demonstrated the best practices of modern database management in aspects of front-end, back-end, and infrastructure.

Besides, speaking of my most impressive open-source project, I built an e-commerce service for Black Friday that supports a high visiting load based on Spring Boot. To filter invalid orders and keep the stability of the service, I implemented a Redis-RocketMQ-MySQL hierarchy. In addition, overselling is prevented by utilizing Redis lock and MySQL optimistic lock to ensure the correct business logic. This project gave me a deeper understanding of how popular e-commerce websites work.

Lastly, I am looking forward to working at a large and innovative IT company like Amazon and hope to have an opportunity for an interview. Thank you for your time and consideration.

Sincerely,

Yi-Chang